RENESAS

HD74ALVCH162830

1-bit to 2-bit Address Driver with 3-state Outputs

REJ03D0040-0200Z (Previous ADE-205-197(Z)) Rev.2.00 Oct.02.2003

Description

This 1-bit to 2-bit address driver is designed for 2.3 V to 3.6 V V_{CC} operation. To ensure the high impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current sinking capability of the driver. Active bus hold circuitry is provided to hold unused or floating inputs at a valid logic level. All outputs, which are designed to sink up to 12 mA, include equivalent 26 Ω resistors to reduce overshoot and undreshoot.

Features

- $V_{CC} = 2.3 \text{ V} \text{ to } 3.6 \text{ V}$
- Typical V_{OL} ground bounce < 0.8 V (@V_{CC} = 3.3 V, Ta = 25°C)
- Typical V_{OH} undershoot > 2.0 V (@V_{CC} = 3.3 V, Ta = 25°C)
- High output current $\pm 12 \text{ mA} (@V_{CC} = 3.0 \text{ V})$
- Bus hold on data inputs eliminates the need for external pullup / pulldown resistors
- All outputs have equivalent 26 Ω series resistors, so no external resistors are required

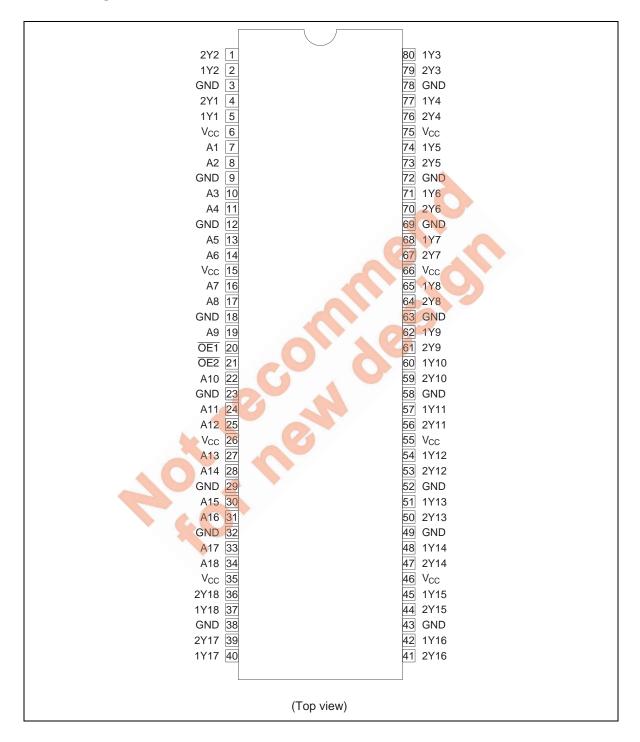


Function Table

Inputs			Outputs	
OE1	OE2	Α	1Yn	2Yn
L	Н	Н	Н	Z
L	Н	L	L	Z
Н	L	Н	Z	Н
Н	L	L	Z	L
L	L	Н	Н	Н
L	L	L	L	L
Н	Н	Х	Z	Z
H : High level L : Low level X : Immaterial Z : High impedance				

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Pin Arrangement





Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V _{CC}	-0.5 to 4.6	V	
Input voltage *1	VI	-0.5 to 4.6	V	
Output voltage *1, 2	Vo	–0.5 to V _{CC} +0.5	V	
Input clamp current	I _{IK}	-50	mA	V ₁ < 0
Output clamp current	Ι _{οκ}	±50	mA	$V_{\rm O}$ < 0 or $V_{\rm O}$ > $V_{\rm CC}$
Continuous output current	lo	±50	mA	$V_{O} = 0$ to V_{CC}
V _{CC} , GND current / pin	I _{CC} or I _{GND}	±100	mA	
Maximum power dissipation at Ta = 55° C (in still air) ^{*3}	P _T	1	W	TVSOP
Storage temperature	T _{stg}	-65 to 150	°C	

Absolute Maximum Ratings

Notes: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

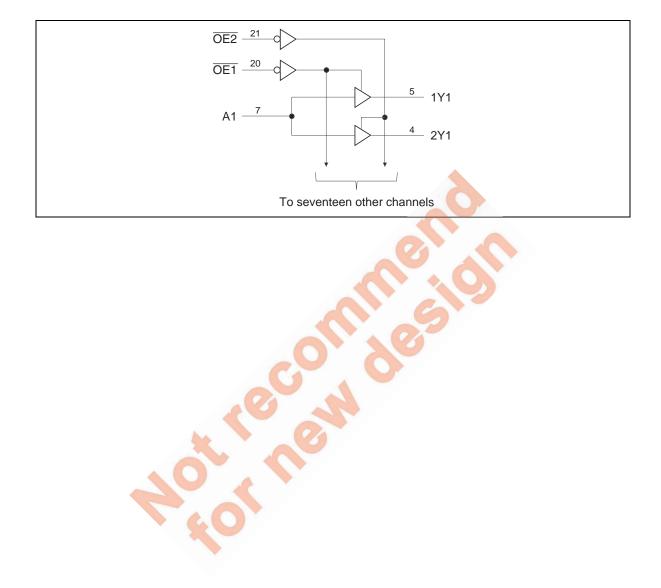
- 1. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- 2. This value is limited to 4.6 V maximum.
- 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage	V _{cc}	2.3	3.6	V	
Input voltage	VI	0	V _{CC}	V	
Output voltage	Vo	0	Vcc	V	
High level output current	Іон	_	-6	mA	V _{CC} = 2.3 V
		_	-8		V _{CC} = 2.7 V
		_	-12		V _{CC} = 3.0 V
Low level output current	I _{OL}	_	6	mA	V _{CC} = 2.3 V
		_	8		V _{CC} = 2.7 V
		_	12		V _{CC} = 3.0 V
Input transition rise or fall rate	$\Delta t / \Delta v$	0	10	ns / V	
Operating temperature	Ta	-40	85	°C	

Note: Unused control inputs must be held high or low to prevent them from floating.

Logic Diagram





Electrical Characteristics

$(Ta = -40 \text{ to } 85^{\circ}C)$

Item	Symbol	V _{cc} (V)	Min	Max	Unit	Test Conditions
Input voltage	VIH	2.3 to 2.7	1.7	_	V	
		2.7 to 3.6	2.0	_	_	
	V _{IL}	2.3 to 2.7	—	0.7	_	
		2.7 to 3.6	—	0.8	_	
Output voltage	V _{OH}	2.3 to 3.6	V _{CC} -0.2	_	V	I _{OH} = −100 μA
		2.3	1.9	_	_	I _{OH} = –4 mA, V _{IH} = 1.7 V
		2.3	1.7	_		$I_{OH} = -6 \text{ mA}, V_{IH} = 1.7 \text{ V}$
		3.0	2.4	_		I _{OH} = –6 mA, V _{IH} = 2.0 V
		2.7	2.0	-		I _{OH} = -8 mA, V _{IH} = 2.0 V
		3.0	2.0	-	S	I _{он} = –12 mA, V _{IH} = 2.0 V
	V _{OL}	2.3 to 3.6	_	0.2		I _{OL} = 100 μA
		2.3	- //	0.4		$I_{OL} = 4 \text{ mA}, V_{IL} = 0.7 \text{ V}$
		2.3	-	0.55	0	$I_{OL} = 6 \text{ mA}, V_{IL} = 0.7 \text{ V}$
		3.0	2	0.55	15	$I_{OL} = 6 \text{ mA}, V_{IL} = 0.8 \text{ V}$
		2.7	U.	0.6		$I_{OL} = 8 \text{ mA}, V_{IL} = 0.8 \text{ V}$
		3.0	-	0.8		$I_{OL} = 12 \text{ mA}, V_{IL} = 0.8 \text{ V}$
Input current	I _{IN}	3.6	-	±5	μΑ	$V_{IN} = V_{CC} \text{ or } GND$
	IIN (hold)	2.3	45	-	_	V _{IN} = 0.7 V
		2.3	-45	_	_	V _{IN} = 1.7 V
		3.0	75	_	_	V _{IN} = 0.8 V
		3.0	-75	_	_	V _{IN} = 2.0 V
		3.6	_	±500	_	$V_{IN} = 0$ to 3.6 V ^{*1}
Off state output current	loz	3.6	_	±10	μΑ	$V_{OUT} = V_{CC}$ or GND
Quiescent supply current	Icc	3.6	_	40	μA	$V_{IN} = V_{CC} \text{ or } GND$
	Δl _{CC}	3.0 to 3.6	—	750	μA	V_{IN} = one input at (V _{CC} -0.6) V, other inputs at V _{CC} or GND

Note: 1. This is the bus hold maximum dynamic current required to switch the input from one state to another.

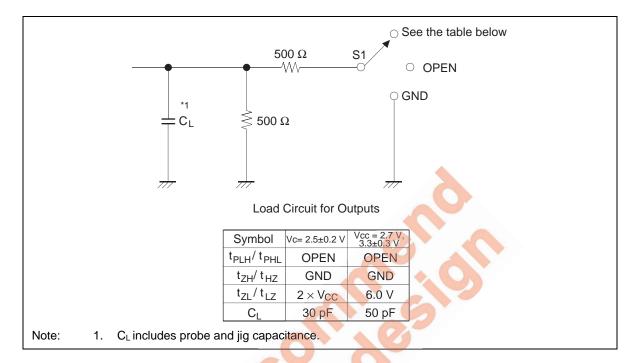


Switching Characteristics

$(Ta = -40 \text{ to } 85^{\circ}C)$

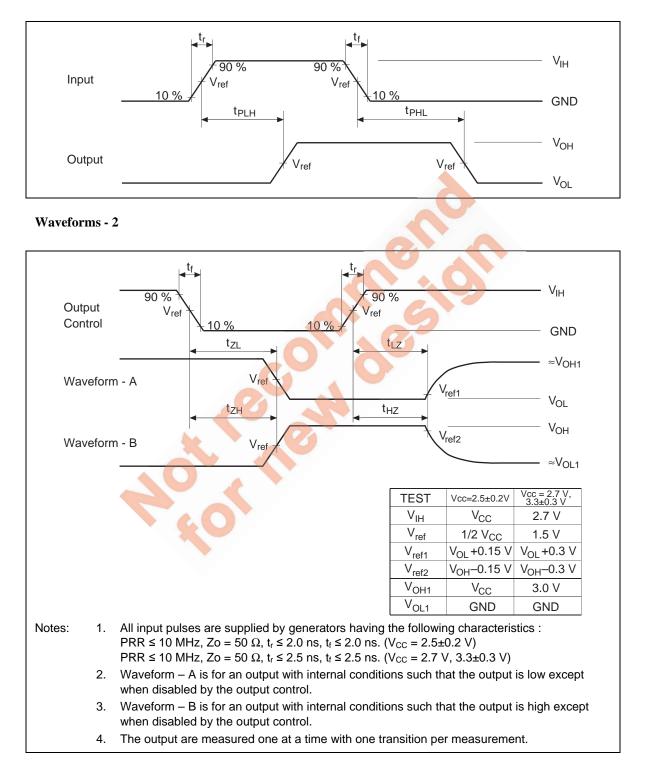


Test Circuit



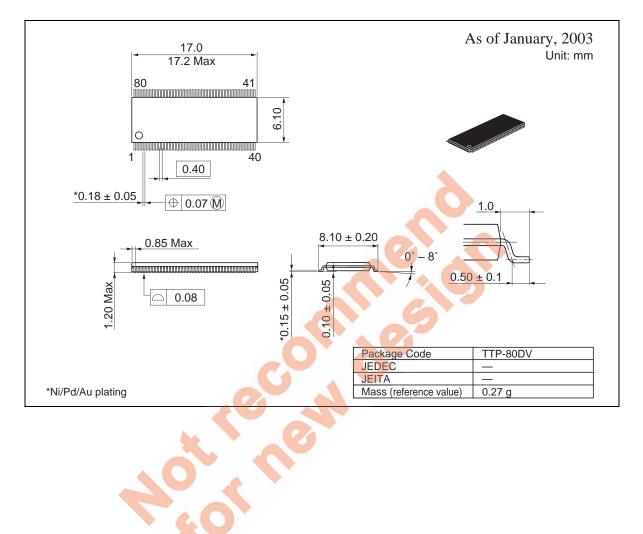


Waveforms - 1





Package Dimensions





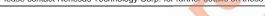
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Renesas Technology Europe Limited.

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

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